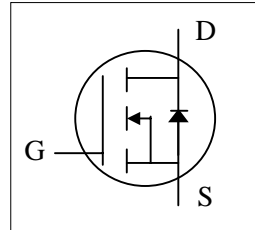




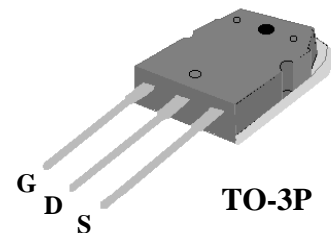
- ▼ Low On-resistance
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic



BV_{DSS}	500V
$R_{DS(ON)}$	0.27Ω
I_D	20A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	500	V
V_{GS}	Gate-Source Voltage	±30	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V	20	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, V_{GS} @ 10V	10	A
I_{DM}	Pulsed Drain Current ¹	80	A
$P_D@T_C=25^\circ C$	Total Power Dissipation	150	W
E_{AS}	Single Pulse Avalanche Energy ²	200	mJ
I_{AR}	Avalanche Current	20	A
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	0.833	°C/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient	40	°C/W



AP18N50W

Electrical Characteristics @T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =1mA	500	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ³	V _{GS} =10V, I _D =10A	-	-	0.27	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2	-	4	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =10A	-	10	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =400V, V _{GS} =0V	-	-	100	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±30V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge ³	I _D =20A	-	94	150	nC
Q _{gs}	Gate-Source Charge	V _{DS} =400V	-	23	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =10V	-	36	-	nC
t _{d(on)}	Turn-on Delay Time ³	V _{DD} =200V	-	113	-	ns
t _r	Rise Time	I _D =10A	-	80	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =50Ω, V _{GS} =10V	-	525	-	ns
t _f	Fall Time	R _D =20Ω	-	100	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	4600	7400	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	350	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	10	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ³	I _S =20A, V _{GS} =0V	-	-	1.3	V
t _{rr}	Reverse Recovery Time ³	I _S =20A, V _{GS} =0V	-	490	-	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	10	-	uC

Notes:

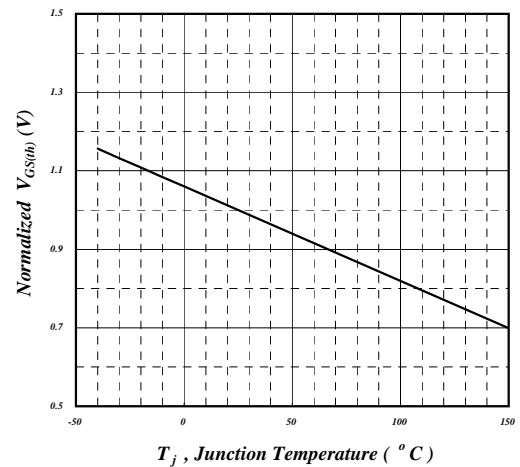
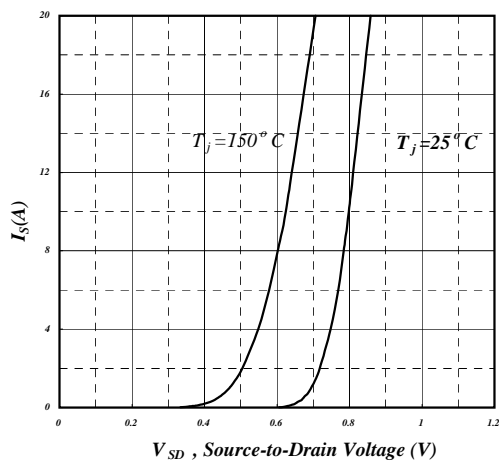
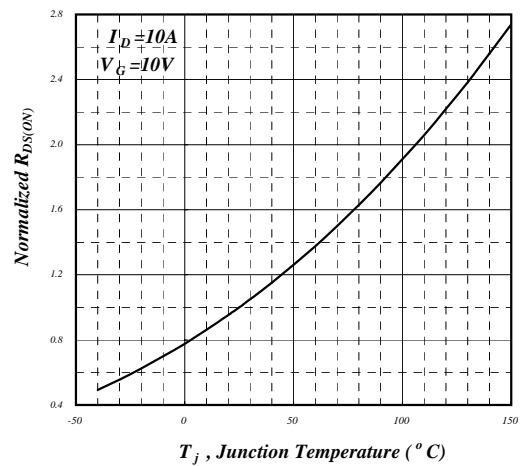
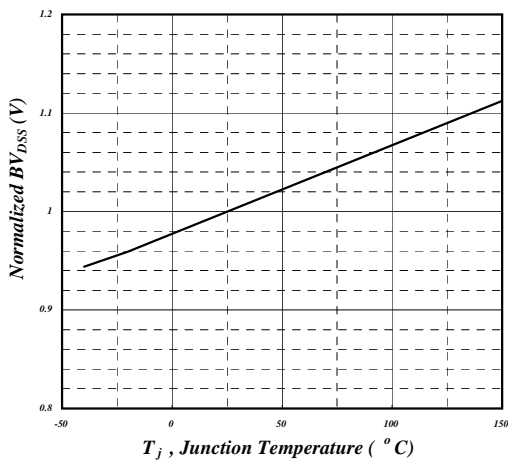
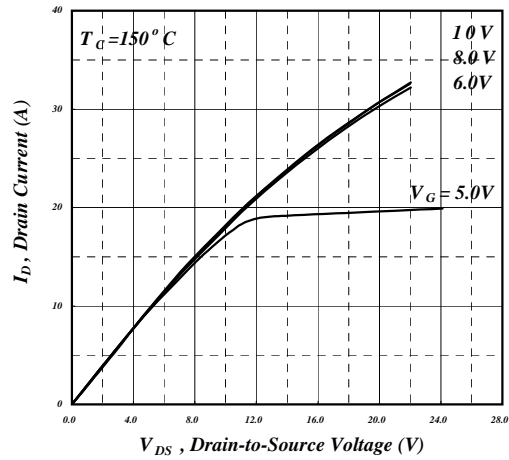
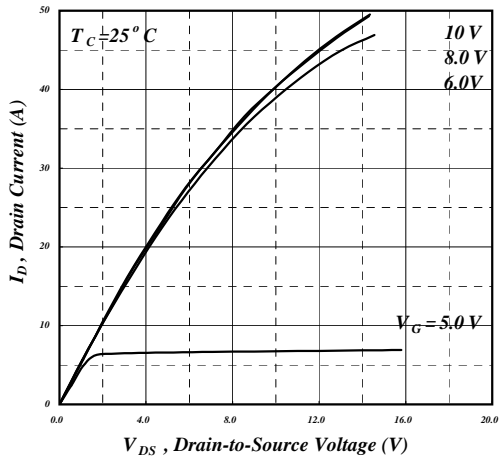
- 1.Pulse width limited by Max junction temperature.
- 2.Starting T_j=25°C , V_{DD}=50V , L=1mH , R_G=25Ω
- 3.Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

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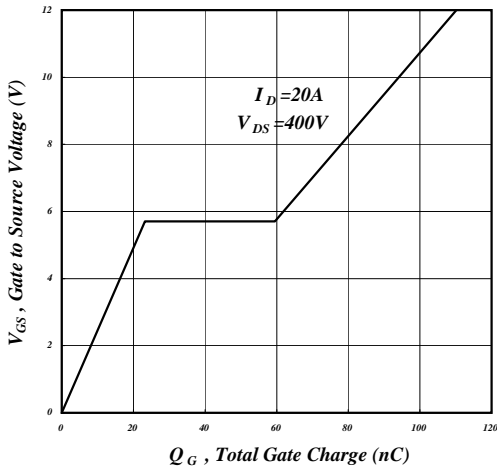


Fig 7. Gate Charge Characteristics

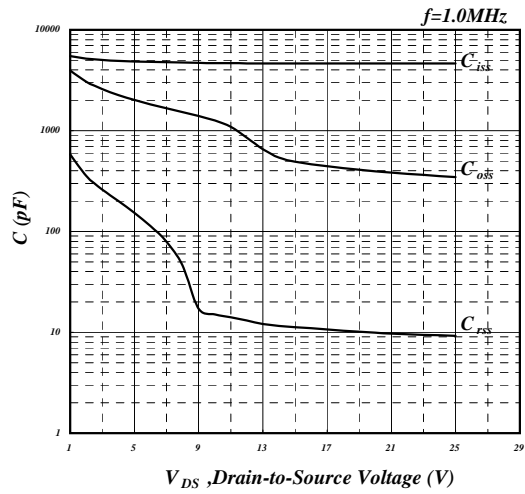


Fig 8. Typical Capacitance Characteristics

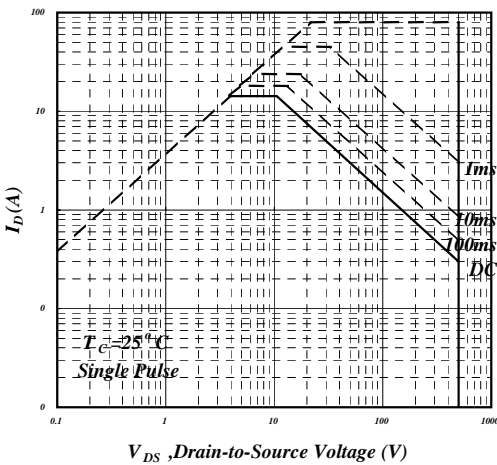


Fig 9. Maximum Safe Operating Area

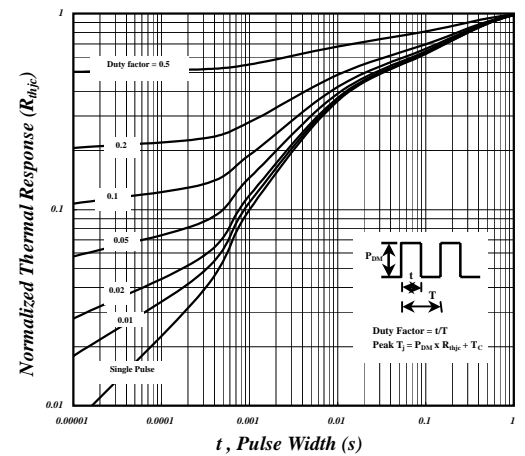


Fig 10. Effective Transient Thermal Impedance

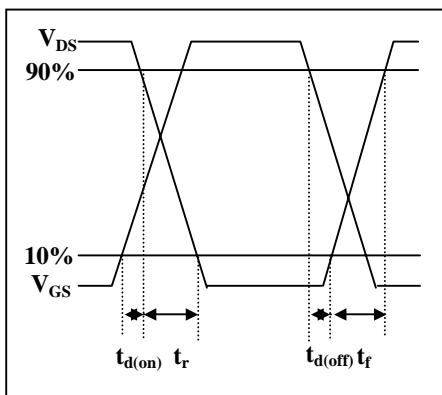


Fig 11. Switching Time Waveform

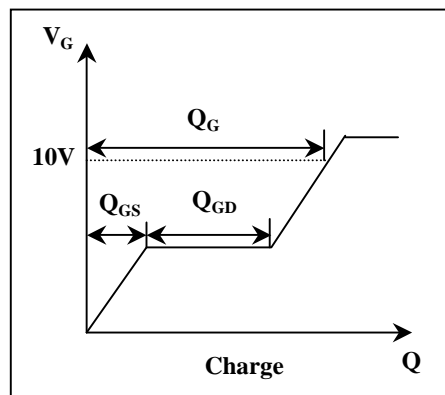


Fig 12. Gate Charge Waveform